

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A manufacturing method of a magnetic head device, comprising:

[[a]] preheating ~~step of by irradiating, with a first laser beam, a laser beam to~~ terminal pads of a magnetic head slider and [[to]] connection pads of a lead conductor member that is to be electrically connected to the magnetic head slider;

~~a supply step of supplying conductive metal material for connecting said terminal pads and said connection pads during or after said preheating~~ [[step]]; [[and]]

[[a]] heating ~~step of performing so as to form~~ molten-metal connections between said terminal pads and said connection pads by irradiating, ~~with a second laser beam, a laser beam to~~ said conductive metal material; and

annealing the conductive metal material with a third laser beam after heating the conductive metal material such that laser energy applied during annealing gradually decreases.

Claim 2 (Currently Amended): The method as claimed in claim 1, wherein said preheating [[step]] comprises irradiating ~~a laser beam the terminal pads and connection pads~~ with an irradiation energy controlled to secure wettability for connections of said conductive metal material.

Claim 3 (Currently Amended): The method as claimed in claim 1, wherein said preheating [[step]] comprises irradiating ~~a laser beam the terminal pads and connection pads~~ with an irradiation energy controlled to stepwise change with ~~the~~ the lapse of time, from a low level to a high level.

Claim 4 (Currently Amended): The method as claimed in claim 1, wherein said preheating [[step]] comprises irradiating a laser beam the terminal pads and connection pads with an irradiation energy controlled so that a temperature of a magnetic head element of said magnetic head slider becomes 150°C or less.

Claim 5 (Withdrawn): The method as claimed in claim 1, wherein said supply step comprises disposing or injecting said conductive metal material so that the conductive metal material abuts on at least either said terminal pads or said connection pads.

Claim 6 (Withdrawn): The method as claimed in claim 1, wherein said supply step comprises supplying solder, solder with core inside, silver or gold.

Claim 7 (Withdrawn): The method as claimed in claim 1, wherein said preheating step comprises preheating dummy terminal pads formed on said magnetic head slider and dummy connection pads to be connected with said dummy terminal pads, wherein said supply step comprises supplying conductive metal material for connecting said dummy terminal pads and said dummy connection pads, and wherein said heating step comprises performing molten-metal connections between said dummy terminal pads and said dummy connection pads by irradiating a laser beam to said conductive metal material for connecting said dummy terminal pads and said dummy connection pads.

Claims 8-18 (Canceled).

Claim 19 (New): The method as claimed in claim 1, wherein the first laser beam is the second laser beam.

Claim 20 (New): The method as claimed in claim 19, wherein the first laser beam, second laser beam, and third laser beam are the same laser beam.

Claim 21 (New): The method as claimed in claim 1, wherein the first laser beam and second laser beam are emitted from a same laser beam supply unit.

Claim 22 (New): The method as claimed in claim 1, wherein the terminal pads and connection pads are simultaneously preheated by the first laser beam.

Claim 23 (New): The method as claimed in claim 1, wherein laser energy applied during heating is substantially constant.

Claim 24 (New): The method as claimed in claim 23, wherein laser energy applied during preheating gradually increases until heating begins.

Claim 25 (New): The method as claimed in claim 23, wherein a minimum laser energy applied during heating is higher than a maximum laser energy applied during annealing.

Claim 26 (New): The method as claimed in claim 1, further comprising tilting the magnetic head device at an angle  $\alpha$  such that the conductive metal material rests partially on the terminal pads and rests partially on the connection pads during heating.